

DISPENSING EQUIPMENT VENDOR CHART

ASYMTEK

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Model: Axiom™ X-1020 **Intro:** Jan. 2002

Footprint: 1100 x 1443mm (43" x 57")* **Principal Use:** Inline production

Applications: Adhesives, encapsulants, underfills, dots

Dispense Area: 432 x 452mm (17" x 17.8") Pump-configuration dependent

Vision System: Pattern recognition with blue & red LEDs

Unique Features: CAN bus structure with local µP control. Integrated needle calibration module that can support both single and dual valve small dot dispensing for a wide variety of fluids, processes and applications.

COOKSON ELECTRONICS EQUIPMENT

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Model: XyflexPro, Small **Intro:** Jan. 2000

Footprint: 787 x 1245mm (31" x 49") **Principal Use:** Inline production, batch, R&D

Applications: Adhesives, encapsulants, underfills, other: SMT solder pastes including no-lead, no-clean pastes, etc.

Dispense Area: 330 x 254mm (13" x 10")

Vision System: Pattern recognition; other: add fiducials and chip edge detection

Unique Features: 31" conveyor, 2 heating zones, max. board size 330mm x 254mm (13" x 10"). Users can reconfigure in under 20 minutes for semiconductor packaging applications, such as underfill or solder paste/adhesive applications.

Model: XyflexPro, Large **Intro:** Jan. 2000

Footprint: 991 x 1575mm (39" x 62") or 1270 x 1575mm (50" x 62")

Principal Use: Inline production, batch, R&D

Applications: Adhesives, dam and fill, encapsulation, epoxy, solder, underfill

Dispense Area: 508 x 559mm (20" x 22")

Vision System: Pattern recognition; other: add fiducials and chip edge detection

Unique Features: 39" conveyor, max. board size 22" x 20" (559mm x 508mm), 39" conveyor, max. board size 8.5" x 10" (216mm x 254mm) or 50" conveyor, max. board size 13" x 10" (330mm x 254mm), all with 3 heating zones.

CREATIVE AUTOMATION COMPANY (Dispensing Division)

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Model: Champion 8300 **Intro:** Dec. 2000

Footprint: 1120 x 1320mm (44" x 54") **Principal Use:** Inline production

Applications: Adhesives, encapsulants, underfills, other: dam & fill, conductive epoxy and solder paste

Dispense Area: 457 x 508mm (18" x 20") **Vision System:** 2D

Unique Features: Digital dispensing with pixel size down to 0.005"

Model: Champion 3700 **Intro:** Dec. 1999

Footprint: 790 x 965mm (31" x 38") **Principal Use:** Inline production, batch, R&D

Applications: Adhesives, encapsulants, underfills, other: dam & fill, conductive epoxy and solder paste

Dispense Area: 457 x 457mm (18" x 18") **Vision System:** 2D

Unique Features: Digital dispensing with pixel size down to 0.005"

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Model: MicroMax **Intro:** Jan. 2001

Footprint: 927 x 1194mm (36.5" x 47")

Principal Use: Inline production, batch, R&D depending on the system configuration

Applications: Adhesives, encapsulants, underfills, other: UV curable materials with onboard UV curing, solder mask, lid attach/heat dissipator attach, 2-part materials with onboard mixing

Dispense Area: 305 x 305mm (12" x 12") w/ two valves, camera and surface sensor

Vision System: 2D, pattern recognition, other: programmable zoom and focus with ClearVu Vision

Unique Features: Taper Lock Mounting allows valve mounting/removal without tools for process and valve changeover. MicroDot Dispensing of solder paste dots at 0.006" (0.152mm), smaller sizes soon. Small fiducials and multi level substrates are located when using ClearVu Vision programmable zoom and focus camera.

Model: DS Series **Intro:** Jan. 1995

Footprint: 1168 x 1067mm (46" x 42")

Principal Use: Inline production, batch, R&D depending on the system configuration

Applications: Adhesives, encapsulants, underfills, other: UV curable materials with onboard UV curing, solder mask, lid attach/heat dissipator attach, 2-part materials with onboard mixing

Dispense Area: 457 x 457mm (18" x 18") w/ one valve, camera and surface sensor

Vision System: 2D, pattern recognition, other: programmable zoom and focus with ClearVu Vision

Unique Features: Taper Lock Mounting allows valve mounting/removal without tools for process and valve changeover. MicroDot Dispensing of solder paste dots at 0.006" (0.152mm), smaller sizes soon. Small fiducials and multi level substrates are located when using ClearVu Vision programmable zoom and focus camera.

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Model: MRSI 175 Uf

Footprint: 889 x 990mm (35" x 39")

Applications: Encapsulants, underfills

Vision System: 2D, pattern recognition

Unique Features: High speed, high accuracy, automatic dispenser with dual lane capability and positive displacement pumps for high performance for semiconductor packaging applications.

Model: MRSI 175 Ag

Footprint: 889 x 990mm (35" x 39")

Applications: Adhesives, underfills, die attach, solder paste

Vision System: 2D, pattern recognition

Unique Features: Process control and dispensing capability for applications including microwav, optical, hybrid, MCM, and IC packaging. Can be configured with 2 positive displacement pumps or 1 positive displacement pump and 1 stamp head.

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KEY

☎ Phone

☎ Fax

📠 Year Founded

* Inches are rounded up